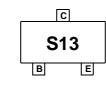


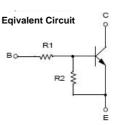
# **FJY3013R NPN Epitaxial Silicon Transistor**

# **Features**

- · Switching circuit, Inverter, Interface circuit, Driver Circuit
- Built in bias Resistor (R1=2.2KΩ, R2=47KΩ)
- Complement to FJY4013R







# Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>CBO</sub>	Collector-Base Voltage	50	V	
V <sub>CEO</sub>	Collector-Emitter Voltage	50	V	
V <sub>EBO</sub>	Emitter-Base Voltage	10	V	
I <sub>C</sub>	Collector Current	100	mA	
T <sub>STG</sub>	Storage Temperature Range	-55~150	٥°	
TJ	Junction Temperature	150	°C	
P <sub>C</sub>	Collector Power Dissipation, by R <sub>0JA</sub>	200	mW	

These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

## Thermal Characteristics\* Ta=25°C unless otherwise noted

Symbol	Parameter	Мах	Units
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient	600	°C/W

Minimum land pad size.

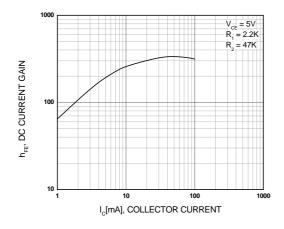
# Electrical Characteristics\* T<sub>c</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	MIN	Тур	MAX	Units
V(BR)CBO	Collector-Emitter Breakdown Voltage	Ic = 10 uA, IE = 0	50			V
V(BR)CEO	Collector-Base Breakdown Voltage	Ic = 100 uA, I <sub>B</sub> = 0	50			V
Ісво	Collector-Cutoff Current	$V_{CB} = 40 \text{ V}, I_E = 0$			0.1	uA
hfe	DC Current Gain	Vce = 5 V, Ic = 5 mA	56			
Vce(sat)	Collector-Emitter Saturation Voltage	Ic = 10 mA, I <sub>B</sub> = 0.5 mA			0.3	V
f⊤	Current Gain - Bandwidth Product	Vce = 10V, Ic = 5 mA		250		MHz
Ccb	Output Capacitance	Vcb = 10 V, IE = 0, f = 1.0 MHz		3.7		pF
VI(off)	Input Off Voltage	Vce = 5 V, Ic = 100uA	0.5			V
VI(on)	Input On Voltage	$V_{CE} = 0.2V, I_{C} = 5mA$			1.1	V
R1	Input Resistor		1.5	2.2	2.9	KΩ
R1/R2	Resistor Ratio		0.042	0.047	0.052	
Pulse Test: PW≤3	300μs, Duty Cycle≤2%					

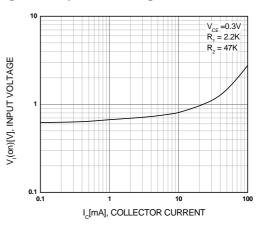
November 2006

# **Typical Performance Characteristics**

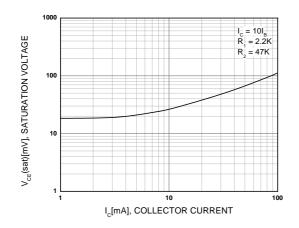
## Figure 1. DC current Gain



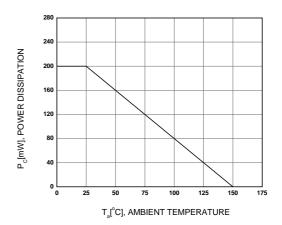
## Figure 2. Input On Voltage

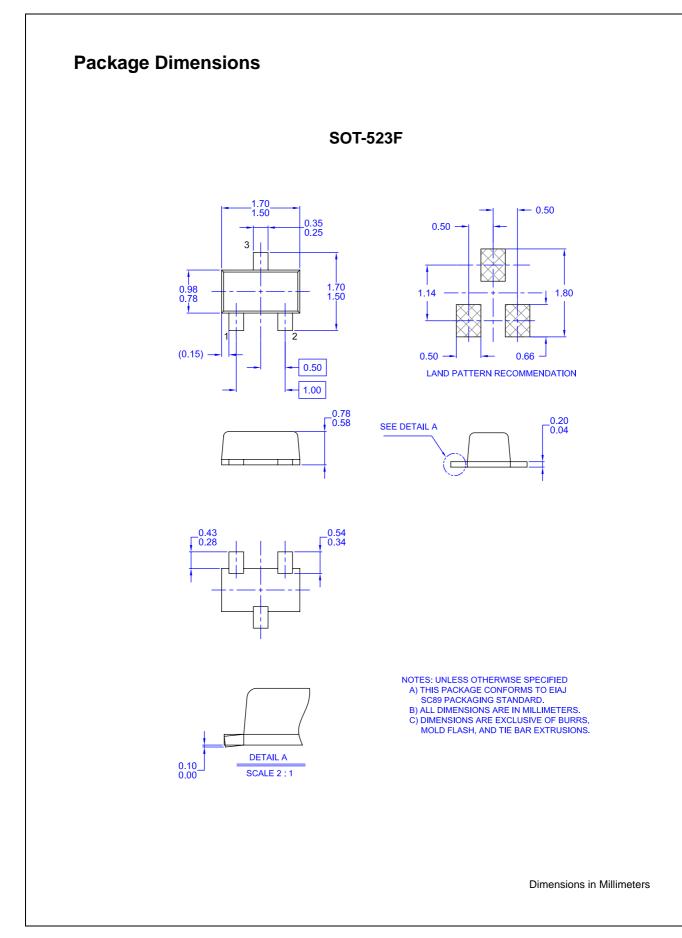


#### Figure 3. Collector-Emitter Saturation Voltage



## Figure 4. Power Derating







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